

GP1A05AJ000F **Series**

Gap: 5mm, Slit: 0.5mm *OPIC Output **Transmissive Photointerrupter** with Connector



Description

GP1A05AJ000F Series are standard, OPIC output, transmissive photointerrupters with opposing emitter and detector in a case, providing non-contact sensing. For this family of devices, the emitter and detector are inserted in a case, and a 3-pin connector is included to allow remote-mount or off-board designs.

■ Features

- 1. Transmissive with OPIC output
- 2. Highlights:
 - · Includes additional screw fixing holes
 - · Positioning Pin to prevent misalignment
- 3. Key Parameters:
 - · Gap Width: 5mm
 - · Slit Width (detector side): 0.5mm
 - Package: 34×18×11mm (without connector and positloning pin)
 - Connector: GP1A05AJ000F; Tyco Electronics

AMP K.K. (PN: 171825-3)

GP1A05A2J00F; J.S.T. Mfg Co., Ltd.

(PN: B3P-SHF-IAA(LF))

GP1A05A5J00F; Molex-Japan Co.,

Ltd. (PN: 5267-03A)

- · Output Type : High when the object is present with Pullup Resistor
- 4. Lead free and RoHS directive compliant

■ Agency approvals/Compliance

1. Compliant with RoHS directive

■ Applications

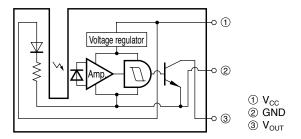
- 1. General purpose detection of object presence or motion.
- 2. Example: PPC, FAX, Printer

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^{* &}quot;OPIC"(Optical IC) is a trademark of the SHARP Corporation. An OPIC consists of a light-detecting element and a signalprocessing



■ Internal Connection Diagram

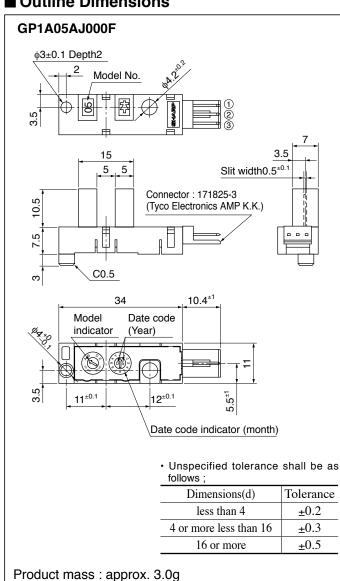


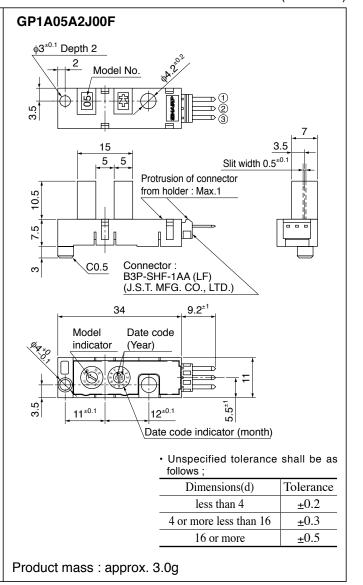
Truth table (In case of external addition pull-up resistance to V_{OUT} terminal)

Condition	Output
Light beam interrupted	High
Light beam uninterrupted	Low

■ Outline Dimensions

(Unit:mm)



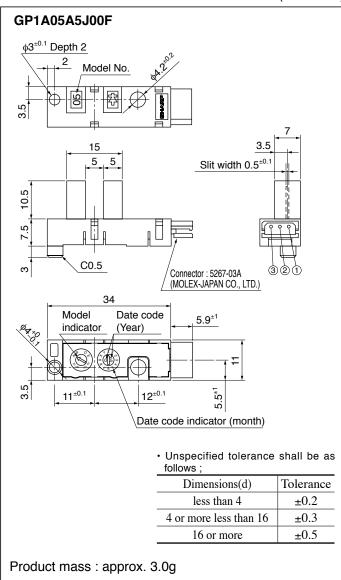


Connector terminal plating material: Sn

Connector terminal plating material: Sn



(Unit:mm)



Connector terminal plating material: Sn



Date code		
Year of production	Month of production	
	Month	Mark
	1	1
	2	2
	3	3
	4	4
T 1:-: 4	5	5
Last two digits of	6	6
Christian year.	7	7
	8	8
	9	9
	10	X
	11	Y
	12	Z

Country of origin

Japan or Philippines (Indicated on the packing case)



■ Absolute Maximum Ratings					
	Parameter			Unit	
Supply	Supply GP1A05AJ000F			v	
voltage	GP1A05A2J00F/GP1A05A5J00F	V_{CC}	-0.5 to +8	v	
*1 Output volt	V _{OUT}	-0.5 to +28	V		
*2 Low level output current			50	mA	
*3 Operating to	Topr	-20 to +75	°C		
*3 Storage temperature			_40 to +85	°C	

^{*1} Collector-emitter voltage of output transistor.

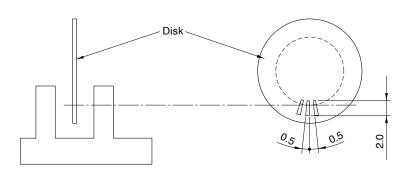
■ Electro-optical Characteristics

/ T I		T 7	T 25	\circ C
(V	CC=3	٧,	$T_a = 25$	C)

Parameter Sy		Symbol	Conditions		TYP.	MAX.	Unit
Low level supply current		I_{CCL}	Light beam uninterrupted		-	30	mA
Low level output voltage		V_{OL}	Light beam uninterrupted, I _{OL} =16mA	_	-	0.35	V
High level supply current I _C		I_{CCH}	Light beam interrupted	_	1	30	mA
High level output voltage		V_{OH}	Light beam interrupted, $R_L=47k\Omega$	$V_{CC} \times 0.9$	ı	_	V
*4 Response frequency		f	R_L =47 $k\Omega$	_	ı	3 000	Hz
Operating supply voltage		V_{CC}	-	4.5	1	5.5	V
*5 Response time	Rise time	t _r	$R_{\rm I} = 280\Omega$	_	0.1	0.5	μs
	Fall time	$t_{\rm f}$	N_=20U\22	_	0.05	0.5	μs

^{*4} Response frequency is measured with the disk shown below being rotated. *5 Refer to Fig.7.





^{*2} Collector current of output transistor, refer to Fig.1.
*3 The connector should be plugged in/out at normal temperature.



Fig.1 Low Level Output Current vs.
Ambient Temperature

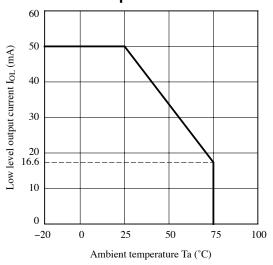


Fig.3 Low Level Output Voltage vs. Ambient Temperature

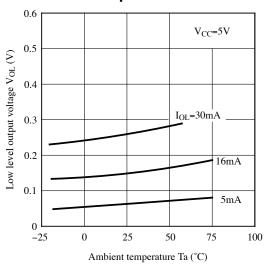


Fig.5 Detecting Position Characteristics (1)

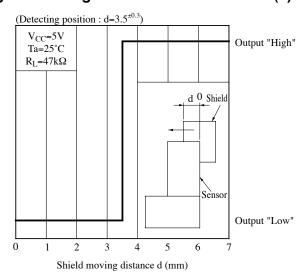


Fig.2 Low Level Output Voltage vs. Low Level Output Current

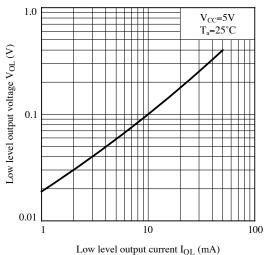


Fig.4 Supply Current vs. Supply Voltage

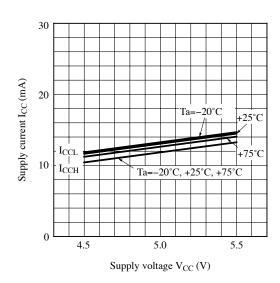


Fig.6 Detecting Position Characteristics (2)

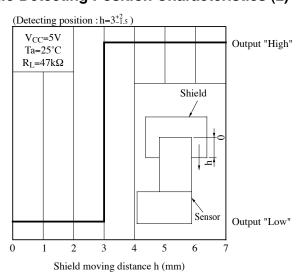
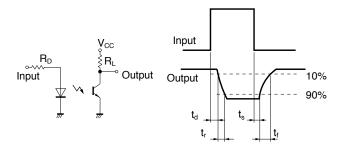




Fig.7 Test Circuit for Response Time



Remarks: Please be aware that all data in the graph are just for reference and not for guarantee.



■ Design Considerations

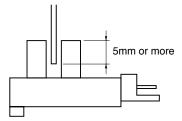
Design guide

1) Prevention of detection error

To prevent photointerrupter from faulty operation caused by external light, do not set the detecting face to the external light.

- 2) In order to stabilize power supply line, connect a by-pass capacitor of more than $0.01\mu F$ between V_{CC} and GND near the device.
- 3) When the sensor is connected with long wire, noise might be on the signal from the sensor while it is going through the wire. To avoid this problem, please evaluate the sensor under actual usage condition to make sure that the system works fine.
- 4) Position of opaque board

Opaque board shall be installed at place 5mm or more from the top of elements. (Example)



5) Screw tightening torque

The tightening torque for screwing should be 0.6N·m or less.

This product is not designed against irradiation and incorporates non-coherent IRED.

Parts

This product is assembled using the below parts.

• Photodetector (qty.: 1) [Using a silicon photodiode as light detecting portion, and a bipolar IC as signal processing circuit]

Category	Maximum Sensitivity wavelength (nm)	Sensitivity wavelength (nm)	Response time (µs)
Photodiode	900	400 to 1 200	3

• Photo emitter (qty.: 1)

Category	Material	Maximum light emitting wavelength (nm)	I/O Frequency (MHz)
Infrared emitting diode (non-coherent)	Gallium arsenide (GaAs)	950	0.3



Material

Case	Connector terminal finish
Black Polcarbonate resin (UL94 HB)	Sn plating

Others

Laser generator is not used.



■ Manufacturing Guidelines

Notes of cleaning

Please carry out neither the immersion cleaning nor the ultrasonic cleaning to avoid the solvent residue inside the case.

When necessary, dust and stain shall clean by air-blow or wipe off by soft cloth soaked in cleaning agent. The cleaning agent used to wipe off must use only the following kind. Ethyl alcohol, Methyl alcohol and Isopropyl alcohol.

Presence of ODC

This product shall not contain the following materials.

And they are not used in the production process for this product.

Regulation substances: CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).

•Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).



■ Package specification

Case package

Package materials

Anti-static plastic bag: Polyethtylene

Moltopren: Urethane

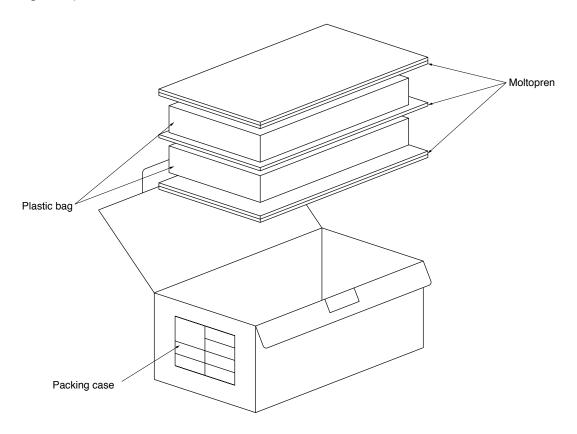
Partition: Corrugated fiberboard
Packing case: Corrugated fiberboard

Package method

75 pcs of products shall be packaged in a plastic bag, Ends shall be sealed by stapler. The bottom of the packing case is covered with moltopren, and the partition is set in the packing case. Each partition should have 1 plastic bag.

Moltopren should be located after all product are settled (1 packing conteains 150 pcs).

Packing composition





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 - --- Office automation equipment
 - --- Telecommunication equipment [terminal]
 - --- Test and measurement equipment
 - --- Industrial control
 - --- Audio visual equipment
 - --- Consumer electronics
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- --- Gas leakage sensor breakers
- --- Alarm equipment
- --- Various safety devices, etc.
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